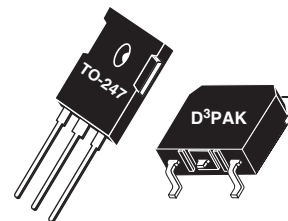


Thunderbolt[®] High Speed NPT IGBT


The Thunderbolt HS[™] series is based on thin wafer non-punch through (NPT) technology similar to the Thunderbolt[®] series, but trades higher $V_{CE(ON)}$ for significantly lower turn-on energy E_{off} . The low switching losses enable operation at switching frequencies over 100kHz, approaching power MOSFET performance but lower cost.

An extremely tight parameter distribution combined with a positive $V_{CE(ON)}$ temperature coefficient make it easy to parallel Thunderbolts HS[™] IGBT's. Controlled slew rates result in very good noise and oscillation immunity and low EMI. The short circuit duration rating of 10 μ s make these IGBT's suitable for motor drive and inverter applications. Reliability is further enhanced by avalanche energy ruggedness. Combi versions are packaged with a high speed, soft recovery DQ series diode.



APT50GS60BR(G) APT50GS60SR(G)

Features

- Fast Switching with low EMI
- Very Low E_{OFF} for Maximum Efficiency
- Short circuit rated
- Low Gate Charge
- Tight parameter distribution
- Easy paralleling
- RoHS Compliant 

Typical Applications

- ZVS Phase Shifted and other Full Bridge
- Half Bridge
- High Power PFC Boost
- Welding
- Induction heating
- High Frequency SMPS



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|----------|--|-----------|---------|
| I_{C1} | Continuous Collector Current $T_C = @ 25^\circ C$ | 93 | A |
| I_{C1} | Continuous Collector Current $T_C = @ 100^\circ C$ | 50 | |
| I_{CM} | Pulsed Collector Current ^① | 195 | |
| V_{GE} | Gate-Emitter Voltage | $\pm 30V$ | V |
| SSOA | Switching Safe Operating Area | 195 | |
| E_{AS} | Single Pulse Avalanche Energy ^② | 280 | mJ |
| t_{SC} | Short Circuit Withstand Time ^③ | 10 | μs |

Thermal and Mechanical Characteristics

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------|--|-----|------|------|--------------|
| P_D | Total Power Dissipation $T_C = @ 25^\circ C$ | - | - | 415 | W |
| $R_{\theta JC}$ | Junction to Case Thermal Resistance | - | - | 0.30 | $^\circ C/W$ |
| $R_{\theta CS}$ | Case to Sink Thermal Resistance, Flat Greased Surface | - | 0.11 | - | |
| T_J, T_{STG} | Operating and Storage Junction Temperature Range | -55 | - | 150 | $^\circ C$ |
| T_L | Soldering Temperature for 10 Seconds (1.6mm from case) | - | - | 300 | |
| W_T | Package Weight | - | 0.22 | - | oz |
| | | - | 5.9 | - | g |
| Torque | Mounting Torque (TO-247), 6-32 M3 Screw | - | - | 10 | in·lbf |
| | | - | - | 1.1 | N·m |



CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should be Followed.

Microsemi Website - <http://www.microsemi.com>

Static Characteristics
T_J = 25°C unless otherwise specified
APT50GS60B_SR(G)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit | |
|--------------------------------------|---|--|------------------------|------|------|-------|----|
| V _{BR(CES)} | Collector-Emitter Breakdown Voltage | V _{GE} = 0V, I _C = 250μA | 600 | - | - | V | |
| V _{BR(ECS)} | Emitter-Collector Breakdown Voltage | V _{GE} = 0V, I _C = 1A | - | 25 | - | | |
| ΔV _{BR(CES)/ΔT_J} | Breakdown Voltage Temperature Coeff | Reference to 25°C, I _C = 250μA | - | 0.60 | - | V/°C | |
| V _{CE(ON)} | Collector-Emitter On Voltage ^④ | V _{GE} = 15V I _C = 50A | T _J = 25°C | - | 2.8 | 3.15 | V |
| | | | T _J = 125°C | - | 3.25 | - | |
| V _{EC} | Diode Forward Voltage ^④ | I _C = 50A | T _J = 25°C | - | 2.15 | - | |
| | | | T _J = 125°C | - | 1.8 | - | |
| V _{GE(th)} | Gate-Emitter Threshold Voltage | V _{GE} = V _{CE} , I _C = 1mA | 3 | 4 | 5 | mV/°C | |
| ΔV _{GE(th)/ΔT_J} | Threshold Voltage Temp Coeff | | - | 6.7 | - | | |
| I _{CES} | Zero Gate Voltage Collector Current | V _{CE} = 600V, V _{GE} = 0V | T _J = 25°C | - | - | 50 | μA |
| | | | T _J = 125°C | - | - | TBD | |
| I _{GES} | Gate-Emitter Leakage Current | V _{GE} = ±20V | - | - | ±100 | nA | |

Dynamic Characteristics
T_J = 25°C unless otherwise specified

| Symbols | Parameter | Test Conditions | Min | Typ | Max | Unit |
|---------------------|---|--|-----|-------|-----|------|
| g _{fs} | Forward Transconductance | V _{CE} = 50V, I _C = 50A | - | 31 | - | S |
| C _{ies} | Input Capacitance | V _{GE} = 0V, V _{CE} = 25V f = 1MHz | - | 2635 | - | pF |
| C _{oes} | Output Capacitance | | - | 240 | - | |
| C _{res} | Reverse Transfer Capacitance | | - | 145 | - | |
| C _{o(cr)} | Reverse Transfer Capacitance Charge Related ^⑤ | V _{GE} = 0V V _{CE} = 0 to 400V | - | 115 | - | |
| C _{o(er)} | Reverse Transfer Capacitance Current Related ^⑥ | | - | 85 | - | |
| Q _g | Total Gate Charge | V _{GE} = 0 to 15V I _C = 50A, V _{CE} = 300V | - | 235 | - | nC |
| Q _{ge} | Gate-Emitter Charge | | - | 18 | - | |
| G _{gc} | Gate-Collector Charge | | - | 100 | - | |
| t _{d(on)} | Turn-On Delay Time | Inductive Switching IGBT and Diode: T _J = 25°C, V _{CC} = 400V, I _C = 50A R _G = 4.7Ω ^⑦ , V _{GG} = 15V | - | 16 | - | ns |
| t _r | Rise Time | | - | 33 | - | |
| t _{d(off)} | Turn-Off Delay Time | | - | 225 | - | |
| t _f | Fall Time | | - | 37 | - | |
| E _{on1} | Turn-On Switching Energy ^⑧ | Inductive Switching IGBT and Diode: T _J = 125°C, V _{CC} = 400V, I _C = 50A R _G = 4.7Ω ^⑦ , V _{GG} = 15V | - | TBD | - | mJ |
| E _{on2} | Turn-On Switching Energy ^⑨ | | - | 1.2 | - | |
| E _{off} | Turn-Off Switching Energy ^⑩ | | - | 0.755 | - | |
| t _{d(on)} | Turn-On Delay Time | Inductive Switching IGBT and Diode: T _J = 125°C, V _{CC} = 400V, I _C = 50A R _G = 4.7Ω ^⑦ , V _{GG} = 15V | - | 33 | - | ns |
| t _r | Rise Time | | - | 33 | - | |
| t _{d(off)} | Turn-Off Delay Time | | - | 250 | - | |
| t _f | Fall Time | | - | 23 | - | |
| E _{on1} | Turn-On Switching Energy ^⑧ | Inductive Switching IGBT and Diode: T _J = 125°C, V _{CC} = 400V, I _C = 50A R _G = 4.7Ω ^⑦ , V _{GG} = 15V | - | TBD | - | mJ |
| E _{on2} | Turn-On Switching Energy ^⑨ | | - | 1.7 | - | |
| E _{off} | Turn-Off Switching Energy ^⑩ | | - | 0.950 | - | |

TYPICAL PERFORMANCE CURVES

APT50GS60B_SR(G)

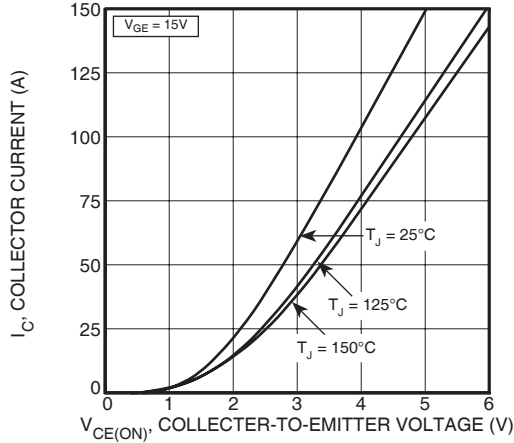


FIGURE 1, Output Characteristics

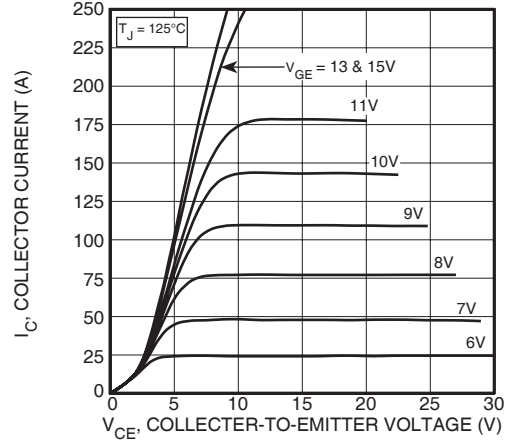


FIGURE 2, Output Characteristics

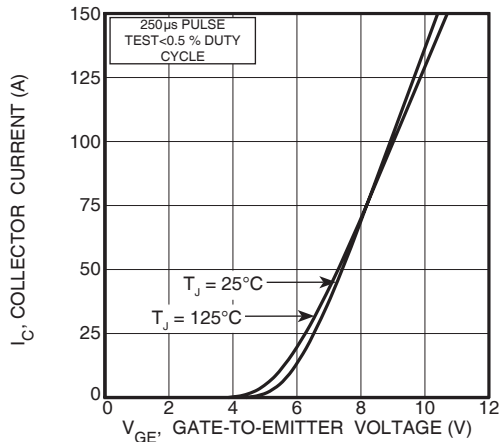


FIGURE 3, Transfer Characteristics

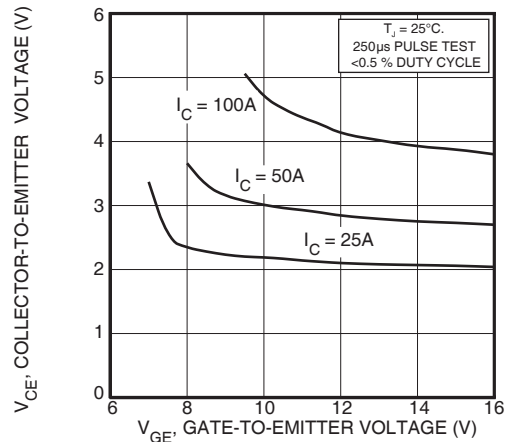


FIGURE 4, On State Voltage vs Gate-to-Emitter Voltage

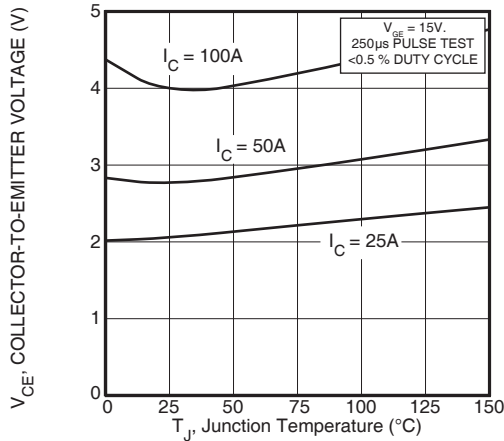


FIGURE 5, On State Voltage vs Junction Temperature

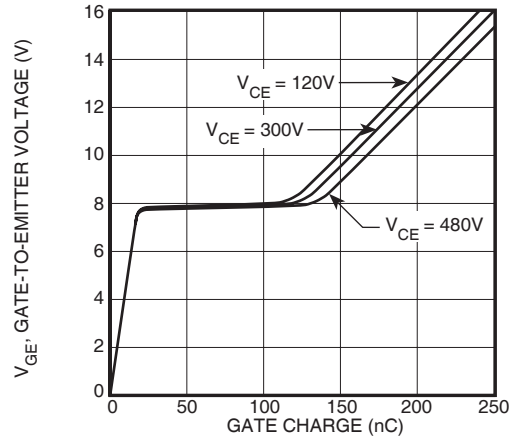


FIGURE 6, Gate Charge

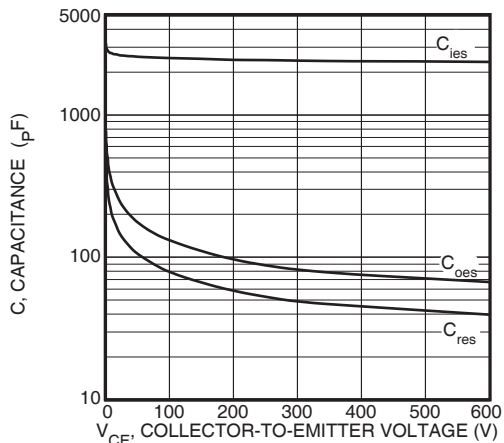


FIGURE 7, Capacitance vs Collector-To-Emitter Voltage

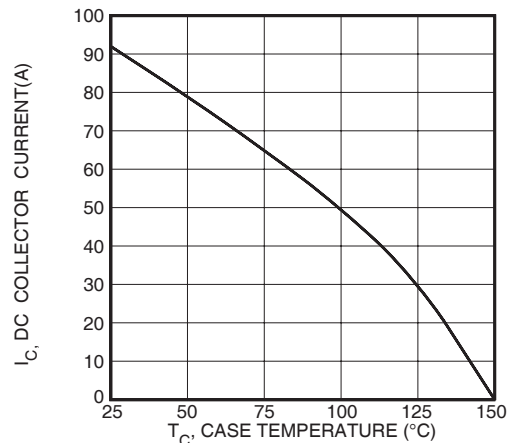


FIGURE 8, DC Collector Current vs Case Temperature

$I_C = 25A$
 $T_J = 25^\circ C$

TYPICAL PERFORMANCE CURVES

APT50GS60B_SR(G)

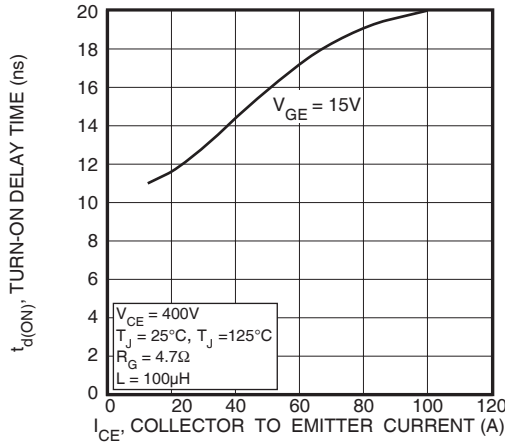


FIGURE 9, Turn-On Delay Time vs Collector Current

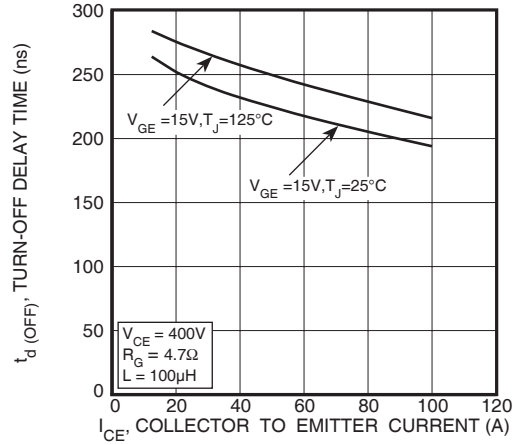


FIGURE 10, Turn-Off Delay Time vs Collector Current

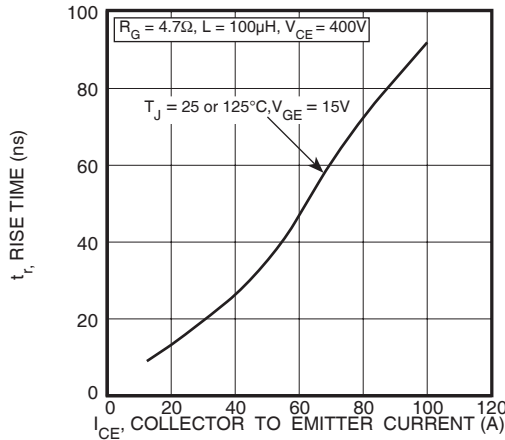


FIGURE 11, Current Rise Time vs Collector Current

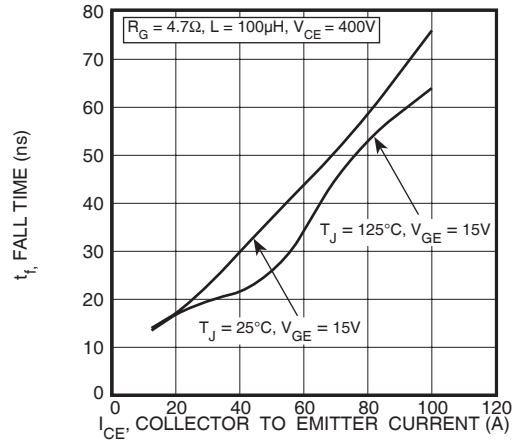


FIGURE 12, Current Fall Time vs Collector Current

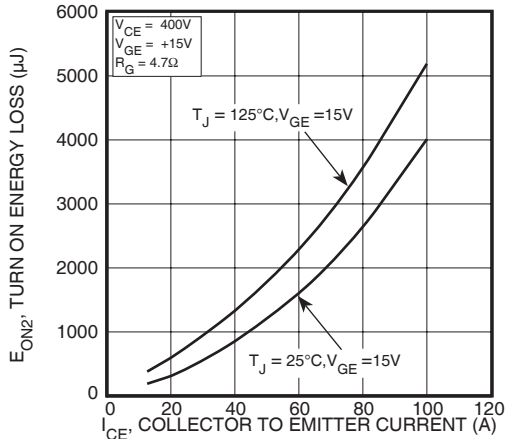


FIGURE 13, Turn-On Energy Loss vs Collector Current

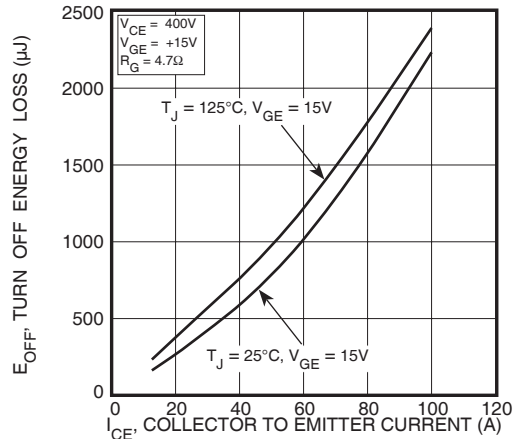


FIGURE 14, Turn Off Energy Loss vs Collector Current

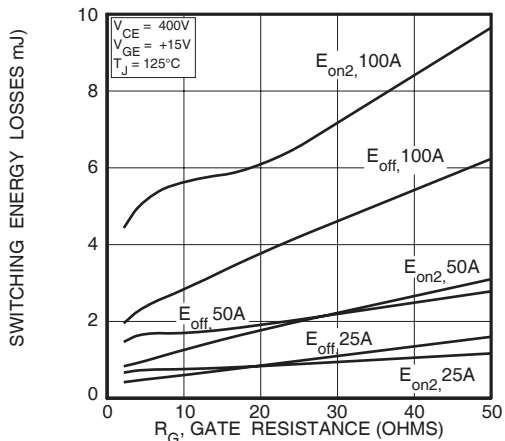


FIGURE 15, Switching Energy Losses vs. Gate Resistance

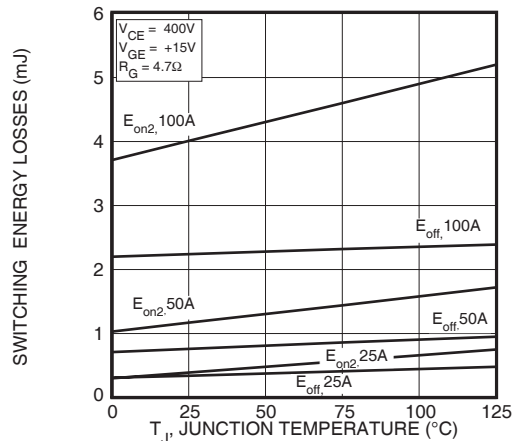
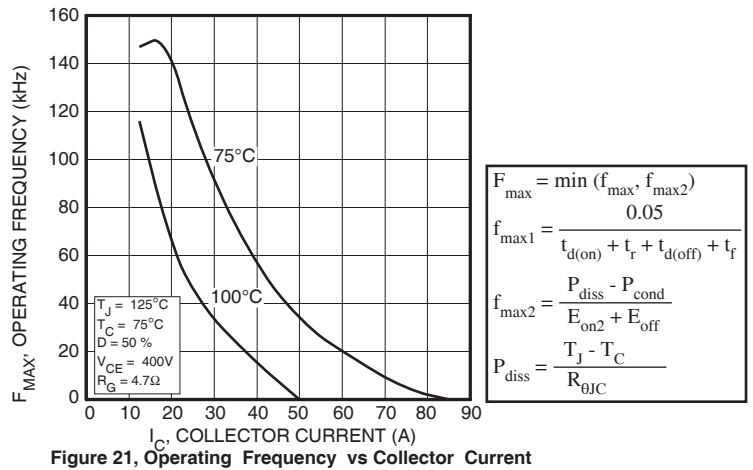
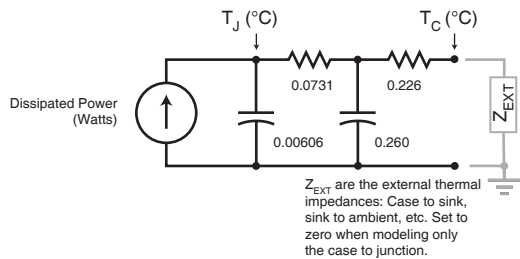
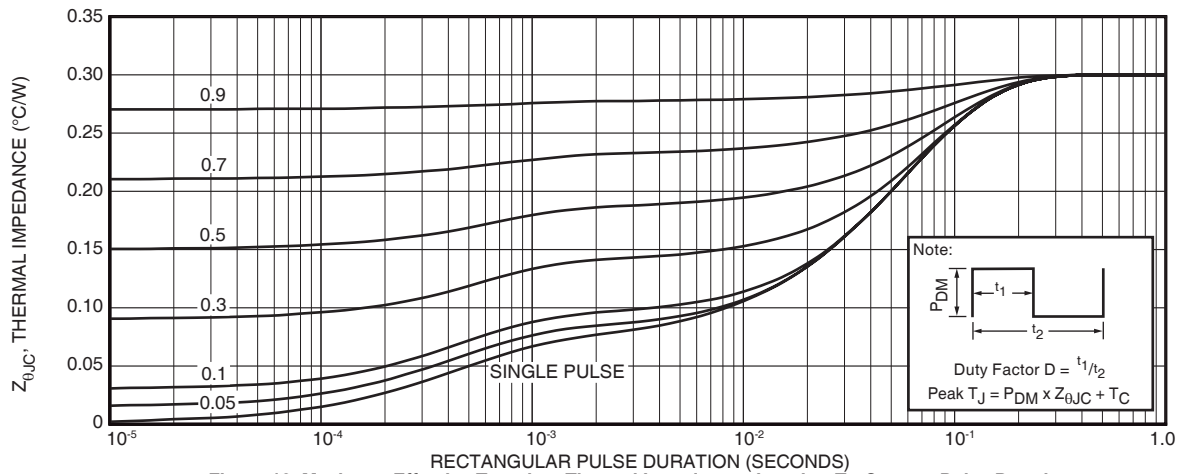
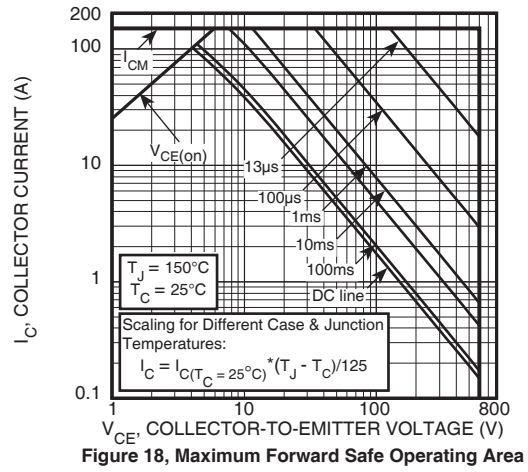
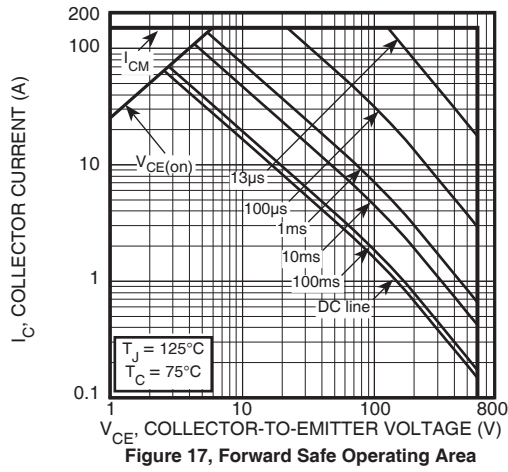


FIGURE 16, Switching Energy Losses vs Junction Temperature



$$F_{max} = \min(f_{max1}, f_{max2})$$

$$f_{max1} = \frac{0.05}{t_{d(on)} + t_r + t_{d(off)} + t_f}$$

$$f_{max2} = \frac{P_{diss} - P_{cond}}{E_{on2} + E_{off}}$$

$$P_{diss} = \frac{T_J - T_C}{R_{\theta JC}}$$

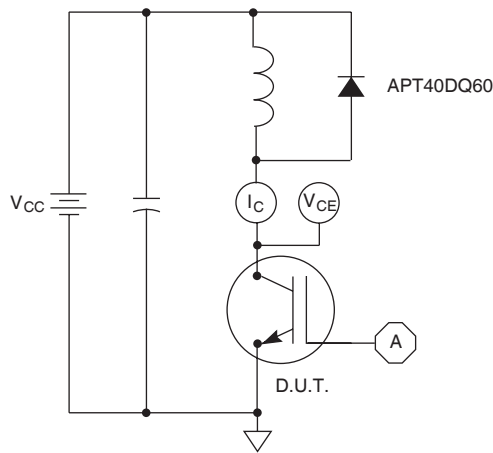


Figure 22, Inductive Switching Test Circuit

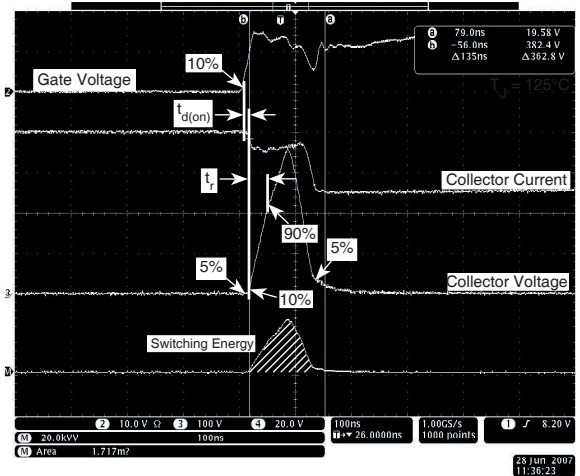


Figure 23, Turn-on Switching Waveforms and Definitions

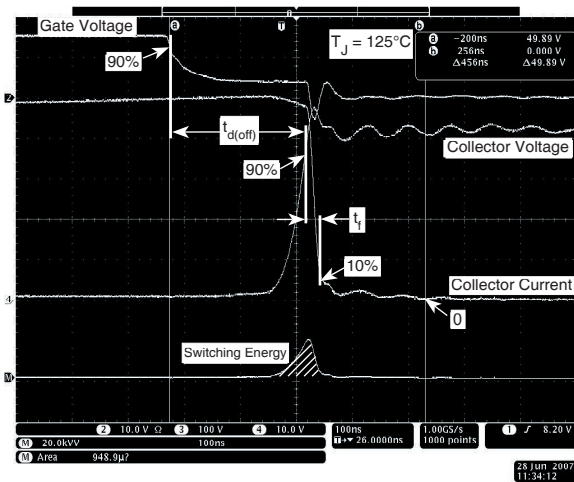


Figure 24, Turn-off Switching Waveforms and Definitions

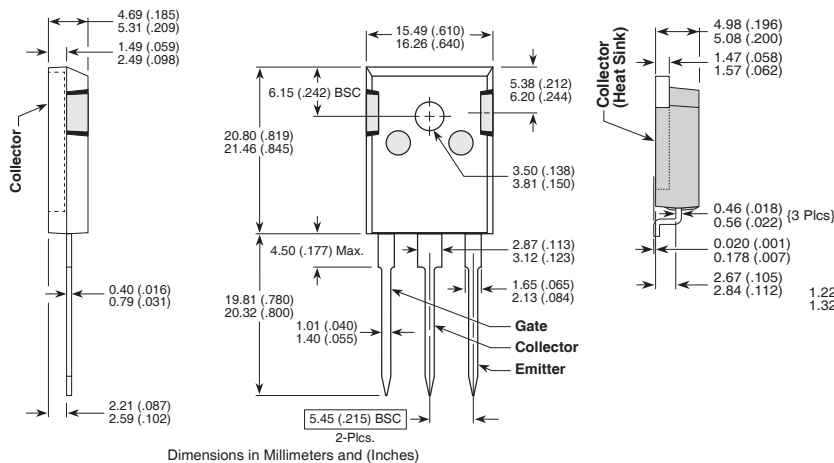
FOOT NOTE:

- ① Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.
- ② Starting at $T_J = 25^\circ\text{C}$, $L = 224\mu\text{H}$, $R_G = 25\Omega$, $I_C = 50\text{A}$
- ③ Short circuit time: $V_{GE} = 15\text{V}$, $V_{CC} \leq 600\text{V}$, $T_J \leq 150^\circ\text{C}$
- ④ Pulse test: Pulse width < $380\mu\text{s}$, duty cycle < 2%
- ⑤ $C_{o(cr)}$ is defined as a fixed capacitance with the same stored charge as C_{oes} with $V_{CE} = 67\%$ of $V_{(BR)CES}$.
- ⑥ $C_{o(er)}$ is defined as a fixed capacitance with the same stored energy as C_{oes} with $V_{CE} = 67\%$ of $V_{(BR)CES}$. To calculate $C_{o(er)}$ for any value of V_{CE} less than $V_{(BR)CES}$, use this equation: $C_{o(er)} = 5.57E-8/V_{DS}^2 + 7.15E-8/V_{DS} + 2.75E-10$.
- ⑦ R_G is external gate resistance, not including internal gate resistance or gate driver impedance (MIC4452).
- ⑧ E_{on1} is the inductive turn-on energy of the IGBT only, without the effect of a commutating diode reverse recovery current adding to the IGBT turn-on switching loss. It is measured by clamping the inductance with a Silicon Carbide Schottky diode.
- ⑨ E_{on2} is the inductive turn-on energy that includes a commutating diode reverse recovery current in the IGBT turn-on energy.
- ⑩ E_{off} is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1.

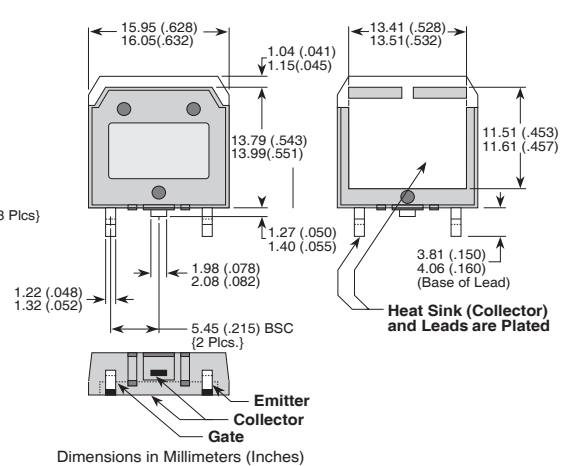
Microsemi reserves the right to change, without notice, the specifications and information contained herein.

TO-247 Package Outline

e1 SAC: Tin, Silver, Copper



D³ Pak Package Outline



Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. US and Foreign patents pending. All Rights Reserved.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru